

MIC-733-A0

AI Inference System based on NVIDIA® Jetson AGX Orin™



Features

- Compact fanless design
- Embedded with NVIDIA® Jetson AGX Orin™ up to 275 TOPS
- Supports 4 x GbE (optional PoE), 4 x USB 3.2 Gen 2 (10Gbit/s)
- Supports 2 x mPCIe, 2 x Nano SIM slots
- Supports Allxon 24/7 remote monitoring and OTA deployment; Azure Certified Devices

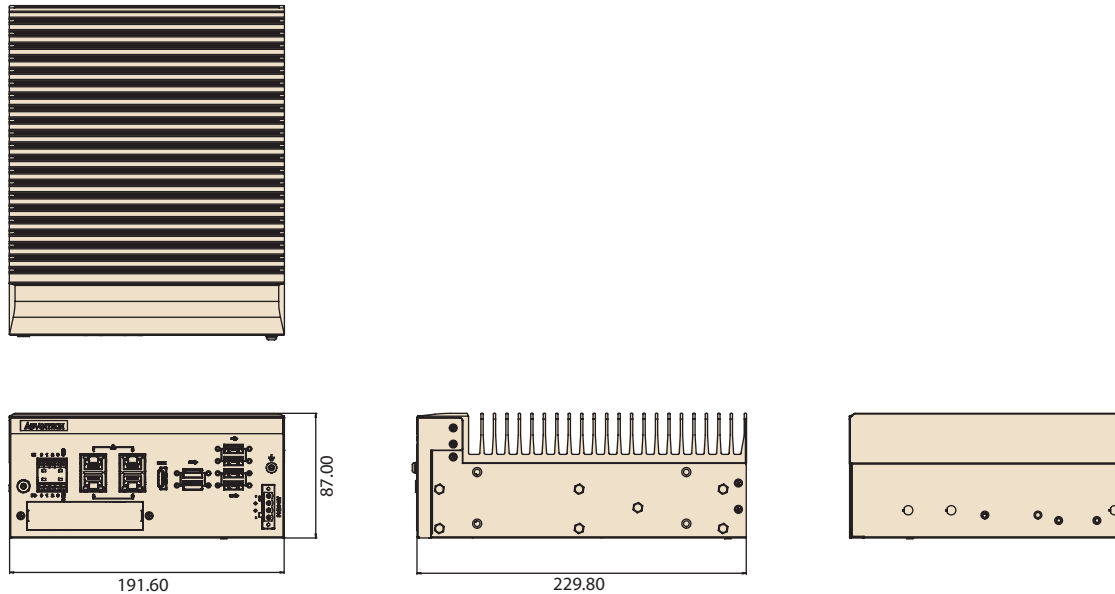
Specifications

		Jetson AGX Orin
Processor	CPU	12-core Cortex A78 ARM 64-bit CPU, 3 clusters (4 x 256KB L2 + 2MB L3) + 4MB L4
	GPU	2048-core NVIDIA Ampere™ GPU with 64 Tensor Cores
	Memory	JAO 64G : 64GB LPDDR5 JAO 32G : 32GB LPDDR5
	Flash	64GB eMMC
I/O	Ethernet	4 x 10/100/1000 Mbps (Optional PoE support, IEEE 802.3af/at)
	Display	HDMI (Max. resolution 3840x2160 @ 60Hz)
	USB	Internal: 1 x USB 2.0 External: 2 x USB 2.0, 4 x USB 3.2 Gen 2
	Digital I/O	4-ch DI, 4-ch DO
	Power Switch	1 x Power ON/OFF Button
	COM	2 x RS-232/422/485 (Internal pin head reserved)
	OTG USB	1 x Micro USB
Expansion	iModule (Optional)	1 x PCIe x8 (MIC-75M10-00A2)
	Mini PCIe	2 x mPCIe (Signal: PCIe+USB)
	SIM	2 x Nano SIM slots
	M.2	1 x M.2 3052 (B-Key, Signal: USB)
	TPM (Optional)	1 x TPM 2.0
	GMSL (Optional)	2 x GMSL2.0 with FAKRA connectors
	iDoor (Optional)	1 x iDoor bracket reserve
Storage	Storage	1 x Micro SD slot 1 x M.2 2280 (M-Key, NVMe, Signal: PCIe x4)
Power	Type	AT/ATX (Default AT)
	Input Voltage	9 ~ 36 V _{DC} , 16-4A
Environment	Operating Temperature	-10 ~ +60 °C with 0.7 m/s airflow (MaxN mode)
	Operating Humidity	95% @ 40 °C (non-condensing)
	Vibration	3Grms @ 5 ~ 500 Hz, random, 1 hr/axis
	Shock	10G / 11 ms
Mechanical	Dimensions (W x D x H)	Core Module: 192 x 230 x 87 mm (7.55" x 9.05" x 3.43") Plus MIC-75M10: 192 x 230 x 111 mm (7.55" x 9.05" x 4.37")
	Weight	4.5 kg
	Installation	Desktop / Wall mount
BSP	Jetpack	Above 5.0
Certifications		UL/CB/CE/FCC/BSMI/CCC (No RED certification)

*Depending on installation situation and interface connection. Derating of max. operating temp. is possible when using the cellular LTE module. Please see user documentation.

Dimensions

Unit: mm



Ordering Information

Part Number	NVIDIA Module	Memory	eMMC
MIC-733-A05A1	AGX Orin	32 GB	64 GB
MIC-733-A06A1	AGX Orin	64 GB	64 GB

Optional

Part Number	Description
96PSA-A230W24P4-3	Adaptor A/D, 100-240V, 230W, 24V
96PSA-A150W19P4-3	Adaptor A/D, 100-240V, 150W, 19V
1702002600	Power Cord (USA) UL/CSA, 3-pin, 10A, 125V, 1.83 M, 180 D
1700029019-01	Power Cord (PSE/BSMI), 3-pin, 7A, 125V, 1.8 M, DAC-ST01
1702002605	Power Cord (EU) 2-pin, 10/16A, 220V, 1.83 M, 90 D
1960065854N001	PCM series module bracket
MIC-75M10-00A2	iModule (1 x PCIe x8)
98RV710AL00	Allxon OOB module

Packing List

Part Number	Description	Quantity
MIC-733-A0	AI Inference System based on NVIDIA Jetson® AGX Orin	1
1652003234	Power terminal block 4P	1
1652005204	DI/DO terminal block 5P	2
1700023619-01	Micro USB cable for system recovery	1
1960070543T007	Mounting bracket	2
1960107065N000	M.2 mPCIe heat spreader bracket	1

Remote Management Enrollment

Enroll in 24/7 secure service to get all the features of remote device management on one centralized cloud portal - Allxon Portal.

*Supports JetPack 4.4 GA and above

Enrollment Page: https://allxon.com/jetson/device_enroll/

Front View

